

Abstract

The invention relates to a radiation curable hot melt composition comprising:

- a) 20 to 100 wt.% of a radiation curable resin or a mixture of radiation curable resins having a viscosity in the range from 15 to 10,000 mPas in the temperature range from 40 to 150°C,
- b) 0 to 50 wt.% of a hydroxyfunctional resin or oligomer or a mixture of hydroxyfunctional resins or oligomers,
- c) 0 to 10 wt.% of a photoinitiator,
- d) 0 to 50 wt.% of fillers and/or additives, and
- e) 0 to 40 wt.% of pigment,

wherein the total amount of components a) to e) adds up to 100 wt.%.

The invention further relates to a process for the coating of a substrate with such radiation curable hot melt composition. In this process the composition is heated to a temperature in the range from 40 to 150°C, is applied to the substrate, and then the coated substrate is exposed to electromagnetic radiation having a wavelength $\lambda \leq 500$ nm.